

GOSTONE ROHS



GMS018N04F1

N-Channel 40V,1.8mΩ max,SGT Power MOSFET

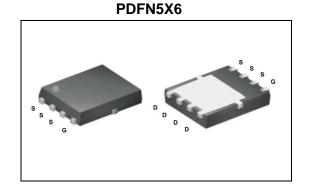
Product Summary						
V _{DS} (V)	$R_{DS(on),max}$ (m Ω)	I _D (A)				
40	1.8 @ V _{GS} = 10V	183 ⁽¹⁾				

Features

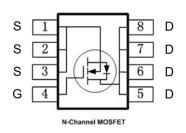
- Low R_{DS(on)} trench technology
- Low thermal impedance
- Fast switching speed
- 100% avalanche tested

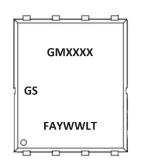
Application

- DC/DC conversion
- Power switch
- Motor drives
- Li- Battery Protection



Equivalent circuit





PDFN5X6

NOTE: LOGO - GS GMXXXXX- Part number code F - Fab location code A - Assembly location code Y - Year code WW - Week code

L&T - Assembly lot code

Absolute maximum rating@25℃

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Parameter			Limit	Unit
Drain-source voltage			40	V
Gate-source voltage		V _{GS}	±20	V
Continuous dusin sumant	Tc=25°C ⁽¹⁾	_	183	А
Continuous drain current	T _C =100°C ⁽¹⁾	I _D	116	
Pulsed drain current ⁽²⁾	·	I _{D,pulse}	619	
Avalanche energy, single pulse ⁽³⁾		E _{AS}	384	mJ
Power dissipation	T _C =25°C	P_{D}	96	W
rowei dissipation	T _A =100°C		38	VV
Operating junction and storage temperature range		T _J , T _{stg}	-55 to 150	°C

Thermal Characteristic

Parameter	Symbol	Max.	Unit	
Thermal resistance, junction-to-case	Steady state	R _{eJC}	1.3	°C/W
Thermal resistance, junction-to-ambient (4)	Steady state	Reja	45	C/VV



Electrical Characteristics (TJ=25 °C unless otherwise noted)

Parameter	Symbol	Test conditions	Min.	Тур.	Max.	Unit	
Static parameter							
Drain to source breakdown voltage	ce breakdown voltage $V_{(BR)DSS}$ $V_{GS} = 0$, $I_D = 250 \mu A$		40			V	
Gate-source threshold voltage	$V_{GS(th)}$	V _{DS} = V _{GS} , I _D = 250 μA	1.2	1.7	2.5	V	
Gate-body leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V			±100	nA	
Zero gate voltage drain current	I _{DSS}	I _{DSS} V _{DS} = 40 V, V _{GS} = 0 V			1	μA	
Drain-source on-resistance	sistance $R_{DS(on)}$ $V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$			1.5	1.8	mΩ	
Forward transconductance (5)	g_{fs}	V _{DS} = 5 V, I _D = 20 A		45		S	
Gate resistance	Rg	f = 1 MHz		1.3		Ω	
Dynamic ⁽⁵⁾							
Total gate charge V _{GS} = 10V	Q_g			44		nC	
Total gate charge V _{GS} = 4.5V	Q_g	$V_{DS} = 20 \text{ V}, I_{D} = 20 \text{ A}, V_{GS} = 10 \text{ V}$		22			
Gate-source charge	Q_{gs}	VDS - 20 V, ID - 20 A, VGS - 10 V		7.8			
Gate-drain charge	Q_{gd}			7.8			
Turn-on delay time	t _{d(on)}			4.7			
Rise time	t _r	V _{DS} = 20 V, I _D = 20 A, V _{GS} = 10 V,		5.2		no	
Turn-off delay time	$t_{\text{d(off)}}$	$R_{GEN} = 3 \Omega$		35		ns	
Fall time	t _f			18		<u>] </u>	
Input capacitance	C _{iss}			2862			
Output capacitance	C_{oss}	V _{DS} = 20 V, V _{GS} = 0 V, f = 1 MHz		1660		pF	
Reverse transfer capacitance	C_{rss}			82			
Reverse Diode Characteristics (5)							
Diode forward voltage	V _{SD}	V _{GS} = 0 V, I _F = 2 A		0.7	1.2	V	
Reverse recovery time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs		49		ns	
Reverse recovery charge	Qrr	- 20 Λ, αι/αι - 100 Λ/μο		54		nC	

Notes

- (1) Limited by maximum junction temperature.
- (2) Pulse width limited by maximum junction temperature.
- (3) $V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, L = 1.0 \text{ mH}.$
- (4) Device mounted on FR-4 substrate PC board with 2oz copper in 1inch square cooling area.
- (5) Guaranteed by design, not subject to production testing.



Typical Performance Characteristics

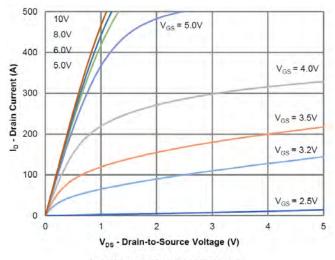


Figure 1: Output Characteristics

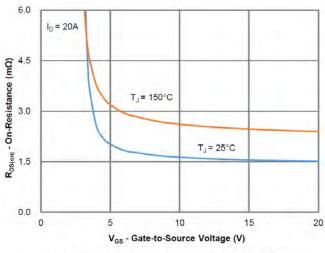


Figure 3: On-Resistance vs. Gate-Source Voltage

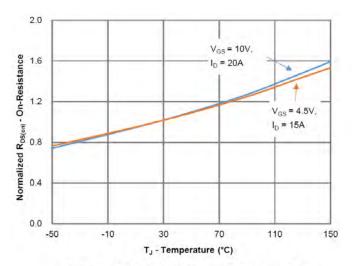


Figure 5: On-Resistance vs. Junction Temperature

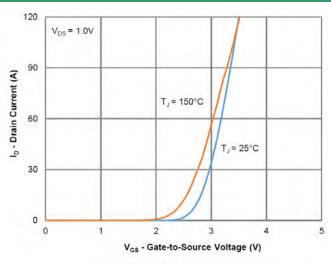


Figure 2: Transfer Characteristics

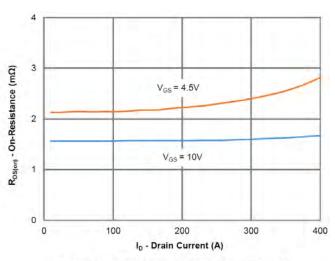


Figure 4: On-Resistance vs. Gate-Source Voltage

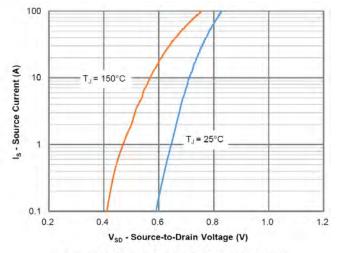


Figure 6: Source-Drain Diode Forward Voltage



Typical Performance Characteristics

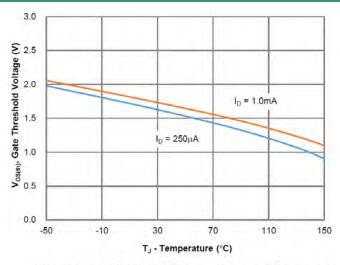


Figure 7: Gate Threshold Variation vs. Junction Temperature

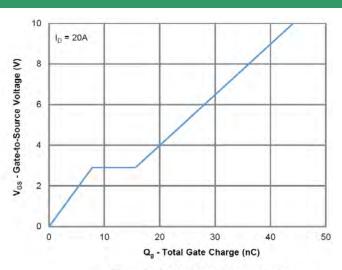


Figure 8: Gate Charge Characteristics

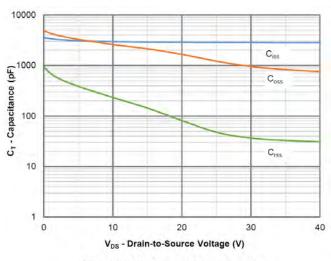


Figure 9: Capacitance Characteristics

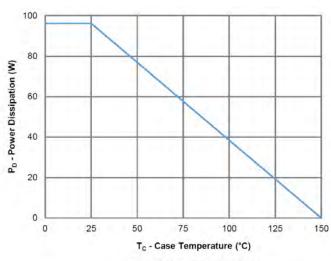


Figure 10: Power Derating

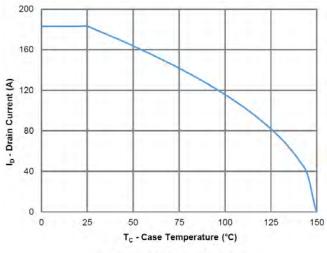


Figure 11: Current Derating

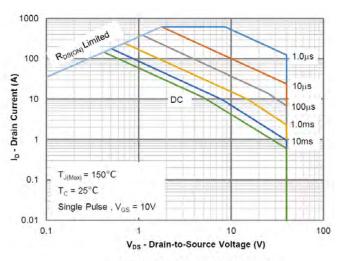


Figure 12: Safe Operating Area



Typical Performance Characteristics

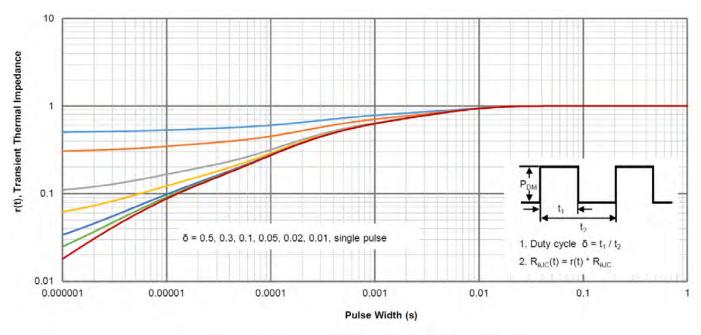
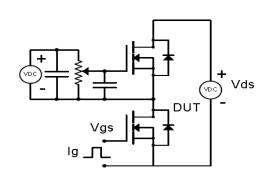


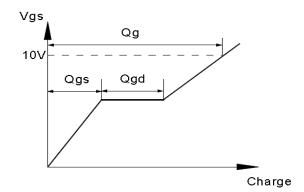
Figure 13: Normalized Maximum Transient Thermal Impedance



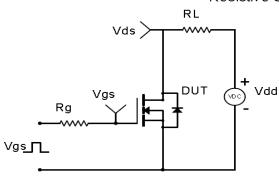
Test Circuit & Waveform

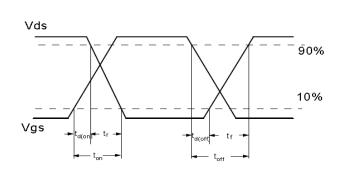
Gate Charge Test Circuit & Waveform



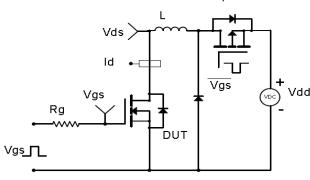


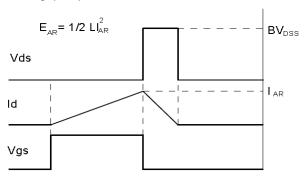
Resistive Switching Test Circuit & Waveforms



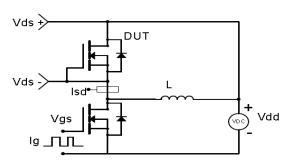


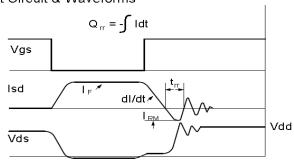
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms





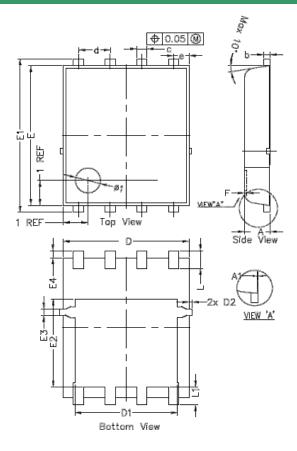
Diode Recovery Test Circuit & Waveforms







Outline Drawing PDFN5X6



Dim	Millimeters				
ווווט	Min	Nom	Max		
А	0.900	1.000	1.100		
A1	0.000		0.050		
b	0.246	0.254	0.312		
С	0.310	0.410	0.510		
d	1.27BSC				
D	4.950	5.050	5.150		
D1	4.000	4.100	4.200		
D2			0.125		
е	0.62BSC				
E	5.500	5.600	5.700		
E1	6.050	6.150	6.250		
E2	3.425	3.525	3.625		
E3	0.150	0.250	0.350		
E4	0.175	0.275	0.375		
F			0.100		
L	0.500	0.600	0.700		
L1	0.600	0.700	0.800		



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